



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

KONISHI et al.

Atty. Ref.: 829-615; Confirmation No. 3539

Appl. No. 10/659,261

TC/A.U. 1722

Filed: September 11, 2003

Examiner: Davis, Robert B.

For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR SEMICONDUCTOR
DEVICES USING THE SAME

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July 24, 2006

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Responsive to the Official Action dated March 22, 2006 (for which petition is hereby
made for a one month extension of time), please amend the above-identified application as
follows: